

DIP FLUXER KIT FASET1

ACCESSORIES

4.304

APPLICATIONS:

SMT

ZEVAC LINE:

ONYX



Dipping Kit for Solder Paste or Flux

- Easier Process and less operator involvement than stencils
- No component or board/pad coplanarity preparation issues
- No adjacent interference issues
- Excellent for extremely fine pitch components
- One set of dipping pedestals replaces dozens of custom component stencils

Utilizing the hot gas nozzle, the BGA is dipped into a defined depth of solder paste or flux using the correct pedestal (depth = approx. 1/2 the sphere diameter of the BGAs) and the paste or flux uniformly coats the solder sphere surfaces.

The dipped component is then aligned and placed. As the board and part are heated, the paste reflows together with the solder sphere for a high quality solder joint.

Uniform solder and flux volume per joint results in consistent process control.

Included with each kit

- Qty 8 - 30x30mm trays of depths:
0.001, 0.002, 0.004, 0.006, 0.008, 0.010, 0.012, 0.015"
(0.025, 0.050, 0.100, 0.150, 0.200, 0.255, 0.305, 0.380mm)
- Qty 2 - 45x45mm trays of depths:
0.008, 0.012"
(0.200, 0.305mm)
- Squeegee blades for 30 and 45mm trays
- Carrying case



Technical Data Subject to Change

ZEVAC - Agent

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